

<IGBT Modules>

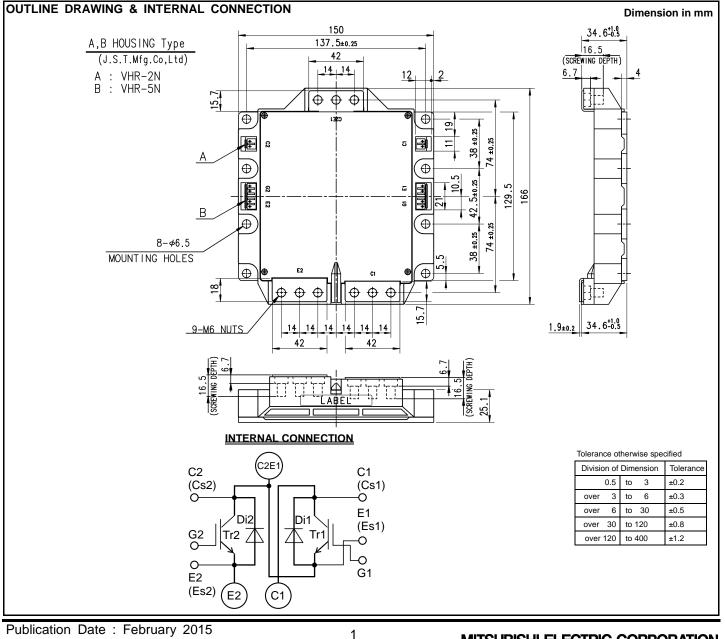
CM1000DUC-34SA

HIGH POWER SWITCHING USE INSULATED TYPE

	Collector current I_C 1 0 0 0 A
	Collector-emitter voltage V _{CES} 1 7 0 0 V
	Maximum junction temperature T _{jmax} 175 °C
	●Flat base Type
	•Copper base plate
	 RoHS Directive compliant
	 Recognized under UL1557, File E323585
dual switch (Half-Bridge)	

APPLICATION

Wind power, Photovoltaic (Solar) power, AC Motor Control, Motion/Servo Control, Power supply, etc.



<IGBT Modules> CM1000DUC-34SA HIGH POWER SWITCHING USE

INSULATED TYPE

MAXIMUM RATINGS (Tj=25 °C, unless otherwise specified)

Symbol	Item	Conditions	Rating	Unit
V _{CES}	Collector-emitter voltage	G-E short-circuited	1700	V
V_{GES}	Gate-emitter voltage	C-E short-circuited	± 20	V
lc	Collector current	DC, T _C =125 °C (Note2, 4)	1000	A
I _{CRM}		Pulse, Repetitive (Note3)	2000	A
P _{tot}	Total power dissipation	T _C =25 °C ^(Note2, 4)	10000	W
IE (Note1)	Emitter current	DC (Note2)	1000	۸
IERM (Note1)	Emitter current	Pulse, Repetitive (Note3)	2000	A
Visol	Isolation voltage	Terminals to base plate, RMS, f=60 Hz, AC 1 min	4000	V
T _{jmax}	Maximum junction temperature	Instantaneous event (overload)	175	°C
T_{cmax}	Maximum case temperature	(Note4)	125	
Tjop	Operating junction temperature	Continuous operation (under switching)	-40 ~ +150	O
T _{stg}	Storage temperature	-	-40 ~ +125	

ELECTRICAL CHARACTERISTICS (T $_j$ =25 °C, unless otherwise specified)

O maked	ltom	Conditions		Limits			Linit
Symbol	Item			Min.	Тур.	Max.	Unit
I _{CES}	Collector-emitter cut-off current	V _{CE} =V _{CES} , G-E short-circuited		-	-	1.0	mA
I _{GES}	Gate-emitter leakage current	V _{GE} =V _{GES} , C-E short-circuited		-	-	10	μA
$V_{\text{GE(th)}}$	Gate-emitter threshold voltage	I _C =100 mA, V _{CE} =10 V		5.4	6.0	6.6	V
		I _C =1000 A ^(Note5) ,	T _j =25 °C	-	1.9	2.4	
V_{CEsat}	Collector-emitter saturation voltage	V _{GE} =15 V,	T _j =125 °C	-	2.1	-	V
		Terminal=chip	T _j =150 °C	-	2.15	-	
Cies	Input capacitance	V _{CE} =10 V, G-E short-circuited		-	-	260	nF
Coes	Output capacitance			-	-	27	
Cres	Reverse transfer capacitance			-	-	5	
Q _G	Gate charge	V _{cc} =1000 V, I _c =1000 A, V _{GE} =15 V		-	4700	-	nC
t _{d(on)}	Turn-on delay time	V _{cc} =1000 V, I _c =1000 A, V _{GE} =±15 V,		-	-	900	- ns
tr	Rise time			-	-	350	
t _{d(off)}	Turn-off delay time			-	-	1250	
t _f	Fall time	- R _G =2.0 Ω, Inductive load		-	-	400	
		I _E =1000 A ^(Note5) ,	T _j =25 ℃	-	4.0	5.2	
V _{EC} (Note1)	Emitter-collector voltage	G-E short-circuited,	T _i =125 °C	-	2.8	-	V
		Terminal=chip	T _i =150 °C	-	2.6	-	
trr (Note1)	Reverse recovery time	V _{cc} =1000 V, I _E =1000 A, V _{GE} =±15 V,		-	-	400	ns
Qrr (Note1)	Reverse recovery charge	$R_{G}=2.0 \Omega$, Inductive load		-	270	-	μC
Eon	Turn-on switching energy per pulse	V _{cc} =1000 V, I _c =I _E =1000 A,		-	239	-	
E _{off}	Turn-off switching energy per pulse	V _{GE} =±15 V, R _G =2.0 Ω,		-	269	-	mJ
Err (Note1)	Reverse recovery energy per pulse	T _i =150 °C, Inductive load		-	130	-	mJ
R _{CC'+EE'}	Internal lead resistance	Main terminals-chip, per switch, T _c =25 °C ^(Note4)		-	0.286	-	mΩ
r _g	Internal gate resistance	Per switch		-	0.56	-	Ω

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HIGH POWER SWITCHING USE INSULATED TYPE

THERMAL RESISTANCE CHARACTERISTICS

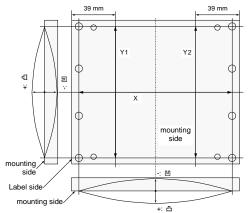
Symbol Item	Itom	Conditions	Limits			Unit
	nem		Min.	Тур.	Max.	Unit
R _{th(j-c)Q}	- Thermal resistance	Junction to case, per IGBT (Note4)	-	-	15	K/kW
R _{th(j-c)D}		Junction to case, per DIODE (Note4)	-	-	24	K/kW
R _{th(c-s)}	Contact thermal resistance	Case to heat sink, per 1/2 module, Thermal grease applied ^(Note4, 6)	-	12	-	K/kW

MECHANICAL CHARACTERISTICS

Symbol Item	ltom	Item Conditions		Limits			Unit
	nem	Conditions		Min.	Тур.	Max.	Unit
Mt	- Mounting torque	Main terminals	M 6 screw	3.5	4.0	4.5	N∙m
Ms		Mounting to heat sink	M 6 screw	3.5	4.0	4.5	N∙m
d _s Creepage distance	Croopage distance	Terminal to terminal		24	-	-	mm
	Creepage distance	Terminal to base plate		33	-	-	mm
d _a Clearance	Clearance	Terminal to terminal		14	-	-	mm
	Clearance	Terminal to base plate		33	-	-	mm
m	mass	-		-	1450	-	g
e _c	Flatness of base plate	On the centerline X, Y1, Y2 (Note7)		-50	-	+100	μm

Note1. Represent ratings and characteristics of the anti-parallel, emitter-collector free wheeling diode (DIODE).

- 2. Junction temperature (T_j) should not increase beyond T_{jmax} rating.
- 3. Pulse width and repetition rate should be such that the device junction temperature (T_j) dose not exceed T_{jmax} rating.
- 4. Case temperature (T_c) and heat sink temperature (T_s) are defined on the each surface (mounting side) of base plate and heat sink just under the chips. Refer to the figure of chip location.
- The heat sink thermal resistance should measure just under the chips.
- 5. Pulse width and repetition rate should be such as to cause negligible temperature rise. Refer to the figure of test circuit.
- 6. Typical value is measured by using thermally conductive grease of λ =0.9 W/(m·K).
- 7. Base plate (mounting side) flatness measurement points (X, Y1 and Y2) are as follows of the following figure.



8. The company name and product names herein are the trademarks and registered trademarks of the respective companies.

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HIGH POWER SWITCHING USE INSULATED TYPE

RECOMMENDED OPERATING CONDITIONS

Symbol Item	ltom	Conditions	Limits			Unit
	nem		Min.	Тур.	Max.	Unit
V _{cc}	(DC) Supply voltage	Applied across C1-E2	-	1000	1200	V
V _{GEon}	Gate (-emitter drive) voltage	Applied across G1-Es1/G2-Es2	13.5	15.0	16.5	V
R _G	External gate resistance	Per switch	2.0	-	6.0	Ω

CHIP LOCATION (Top view)

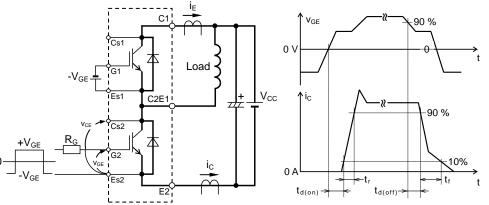
Dimension in mm, tolerance: ±1 mm 111.1 œ ი 99.1 50. 38. 0 Œ \bigcirc \bigcirc \bigcirc \bigcirc 0 \oplus \oplus CZEJ 119.3 Tr2—Di2-Di1—Tr1 -106.2-Tr2—Di2-Di1—Tr1 (38) 5 2 Цъ -Tr2 – Di2-Di1—Tr1 93.2 \oplus \oplus 77.8-Tr2-Di2-Di1-Tr1 a R μ (129.5) в 5) (166) (42. 64.7--Tr2 – Di2-Di1—Tr1 8 R 5 51.7-Tr2-Di2 Di1—Tr1 \oplus \oplus 36.3-Tr2-Di2-Di1-Tr1 (38) 23.2 Tr2-Di2-Di1-Tr1 -Tr2 - Di2-10.2-Di1—Tr1 \oplus ٢ ٢ \oplus C1 0ф \bigcirc \bigcirc \oplus \bigcirc \oplus \oplus (137.5) (150) LABEL SIDE

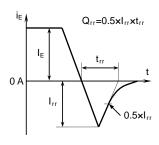
Tr1/Tr2: IGBT, Di1/Di2: DIODE

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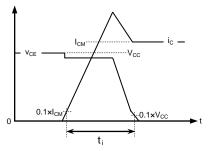
HIGH POWER SWITCHING USE INSULATED TYPE

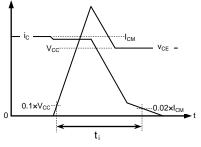
TEST CIRCUIT AND WAVEFORMS



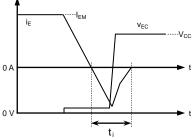


Switching characteristics test circuit and waveforms





trr, Qrr test waveform

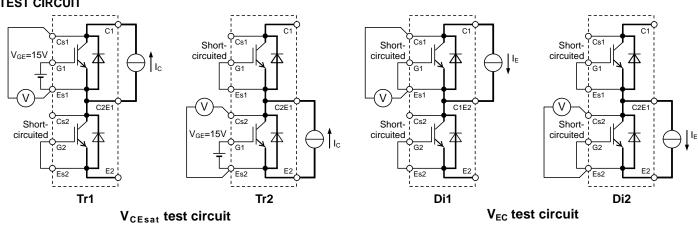


IGBT Turn-on switching energy

IGBT Turn-off switching energy Turn-on / Turn-off switching energy and Reverse recovery energy test waveforms (Integral time instruction drawing)

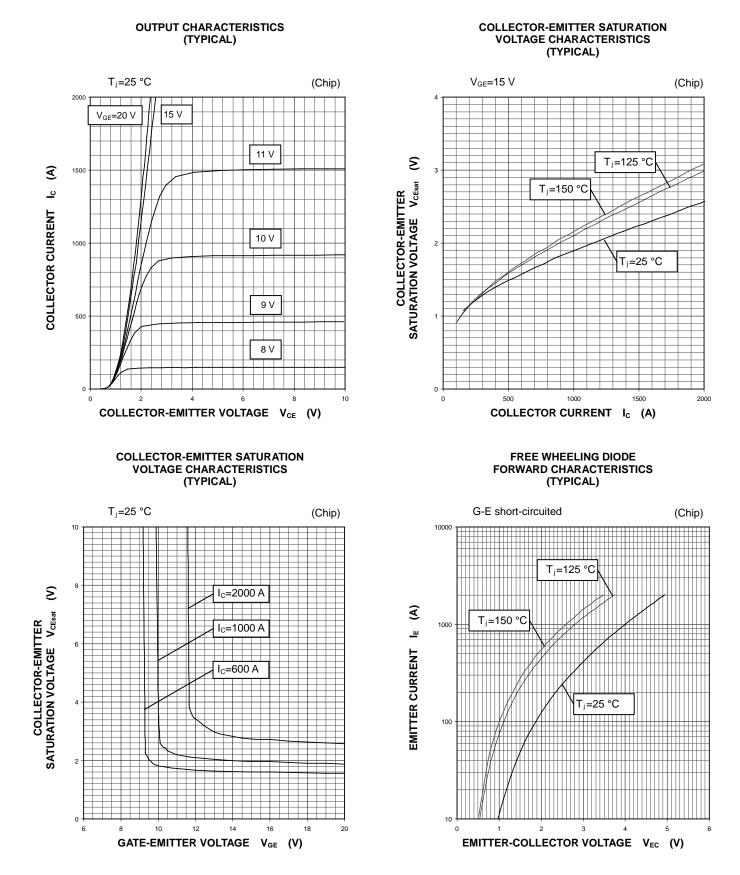
DIODE Reverse recovery energy

TEST CIRCUIT



<IGBT Modules> CM1000DUC-34SA HIGH POWER SWITCHING USE INSULATED TYPE

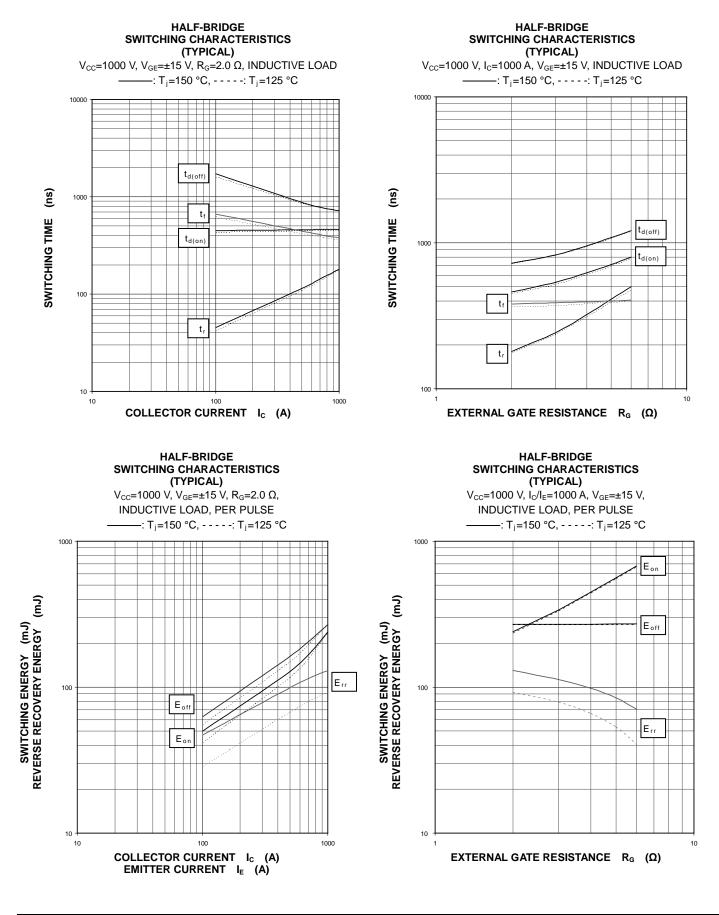
PERFORMANCE CURVES



<IGBT Modules> CM1000DUC-34SA HIGH POWER SWITCHING USE

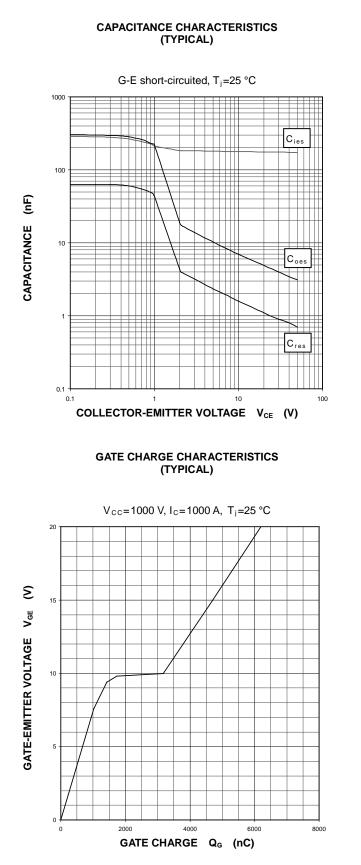
INSULATED TYPE

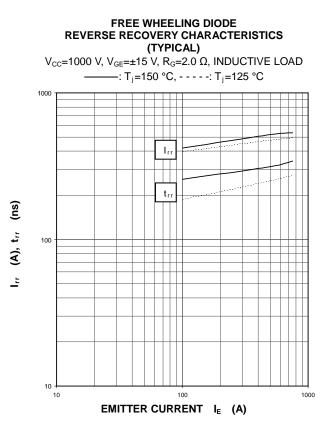
PERFORMANCE CURVES



<IGBT Modules> CM1000DUC-34SA HIGH POWER SWITCHING USE INSULATED TYPE

PERFORMANCE CURVES





TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (MAXIMUM)

Single pulse, $T_C=25^{\circ}C$

 $R_{th(j-c)Q}$ =15 K/kW, $R_{th(j-c)D}$ =24 K/kW

Z_{th(j-c)} NORMALIZED TRANSIENT THERMAL IMPEDANCE 0.1 0.01

0.001

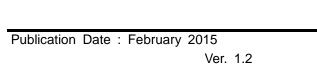
0.00001

0 0001

0.001

0.01

TIME (S)



0.1

10

1

Keep safety first in your circuit designs!

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